



## Material Content Data Sheet



<b>Sales Product Name</b>		BFP 193 E6327		<b>Issued</b>		29. August 2013		
<b>MA#</b>		MA000787250						
<b>Package</b>		PG-SOT143-4-2		<b>Weight*</b>		11.19 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	noble metal	gold	7440-57-5	0.002	0.02		161	
	non noble metal	tin	7440-31-5	0.000	0.00		42	
	inorganic material	silicon	7440-21-3	0.016	0.14	0.16	1405	1608
leadframe	inorganic material	silicon	7440-21-3	0.001	0.01		77	
	non noble metal	titanium	7440-32-6	0.004	0.04		387	
	non noble metal	chromium	7440-47-3	0.013	0.12		1160	
	non noble metal	copper	7440-50-8	4.310	38.52	38.69	385172	386796
wire	noble metal	gold	7440-57-5	0.010	0.09	0.09	864	864
encapsulation	organic material	carbon black	1333-86-4	0.105	0.94		9406	
	inorganic material	antimonytrioxide	1309-64-4	0.158	1.41		14108	
	plastics	brominated resin	-	0.197	1.76		17636	
	plastics	epoxy resin	-	1.645	14.70		146963	
	inorganic material	silicondioxide	60676-86-0	4.473	39.96	58.77	399740	587853
leadfinish	non noble metal	tin	7440-31-5	0.217	1.94	1.94	19356	19356
plating	noble metal	silver	7440-22-4	0.039	0.35	0.35	3523	3523
*deviation	< 10%		Sum in total:			100,00		1000000

### Important Remarks:

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